

TPDH40S120C1P

Silicon Carbide Schottky Diode

General Description

Topdiode 40A 1200V SiC diode is an ultrahigh performance power Schottky diode designed for power electronics systems, where high efficiency and high reliability are required. SiC diodes can be easily paralleled to meet various application demands, without concern of thermal runaway. In combination with the reduced cooling requirements and improved thermal performance, SiC diodes are able to provide lower overall system costs in a variety of diverse applications.

Features

Zero Reverse Recovery Current

Positive Temperature Coefficient on V_F

Temperature-Independent Switching

175°C Operating Junction Temperature

Reduction of Heat Sink Size

Low Switching Losses

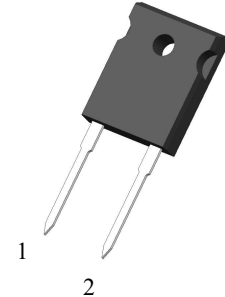
Applications

Switch Mode Power Supplies

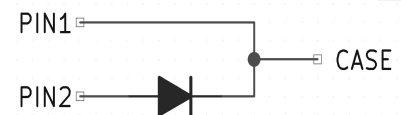
Power Factor Correction

Motor Drive, PV Inverter, Wind Power Station

Package TO-247-2



Equivalent Schematic



Summary

Symbol	Value
$I_{F(AV)}$	40A@143°C
V_{RRM}	1200V
$V_{F(typ.)}$	1.5V
$Q_{C(typ.)}$	190nC

Maximum ratings ($T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	$T_C=25^\circ\text{C}$	1200	V
V_{RSM}	Surge Peak Reverse Voltage	$T_C=25^\circ\text{C}$	1200	V
V_{DC}	DC Blocking Voltage	$T_C=25^\circ\text{C}$	1200	V
I_F	Continuous Forward Current	$T_C=25^\circ\text{C}$	131	A
		$T_C=143^\circ\text{C}$	40	A
I_{FSM}	Non-Repetitive Peak Forward Surge Current	$T_C=25^\circ\text{C}$, $t_p=10\text{ms}$, Half Sine Wave	250	A
P_{tot}	Power Dissipation	$T_C=25^\circ\text{C}$	338	W
T_J, T_{stg}	Operating Junction and Storage Temperature		-55 to +175	$^\circ\text{C}$
M	TO-247 Mounting Torque	M3 Screw	1	Nm

Thermal Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit
R_{thJC}	Thermal Resistance from Junction to Case		0.53		$^\circ\text{C}/\text{W}$
T_{sld}	Soldering Temperature		260		$^\circ\text{C}$

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F=40\text{A}$ $T_J=25^\circ\text{C}$		1.5	1.8	V
		$I_F=40\text{A}$ $T_J=175^\circ\text{C}$		2.0	2.3	V
I_R	Reverse Current	$V_R=1200\text{V}$ $T_J=25^\circ\text{C}$		2	100	μA
		$V_R=1200\text{V}$ $T_J=175^\circ\text{C}$		14	200	μA
Q_C	Total Capacitive Charge	$V_R=800\text{V}$ $T_J=25^\circ\text{C}$		190		nC
C	Total Capacitance	$V_R=0\text{V}$ $T_J=25^\circ\text{C}$ $f=1\text{MHz}$		2734		pF
		$V_R=400\text{V}$ $T_J=25^\circ\text{C}$ $f=1\text{MHz}$		178		pF
		$V_R=800\text{V}$ $T_J=25^\circ\text{C}$ $f=1\text{MHz}$		131		pF
E_C	Capacitance Stored Energy	$V_R=800\text{V}$		54.8		μJ

Typical Performance

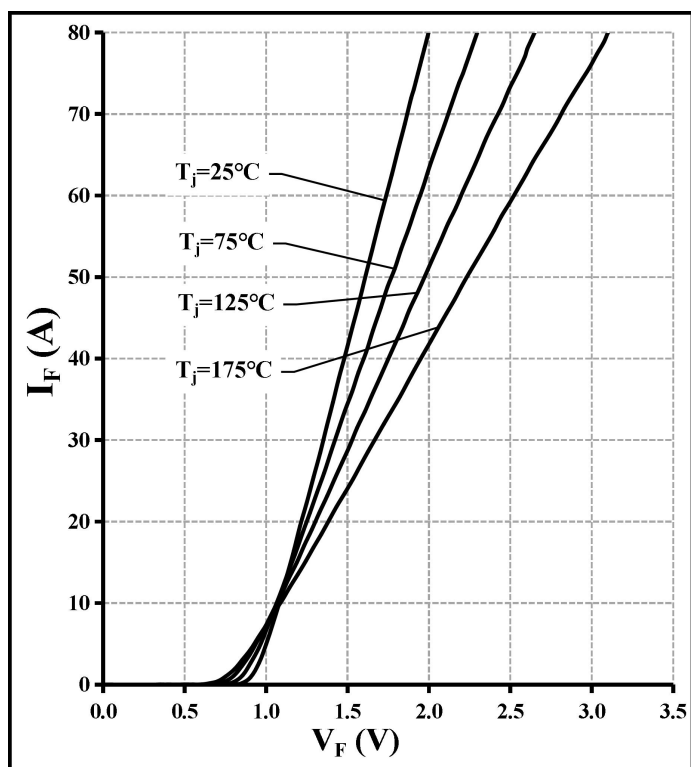


Figure 1: Forward Characteristics

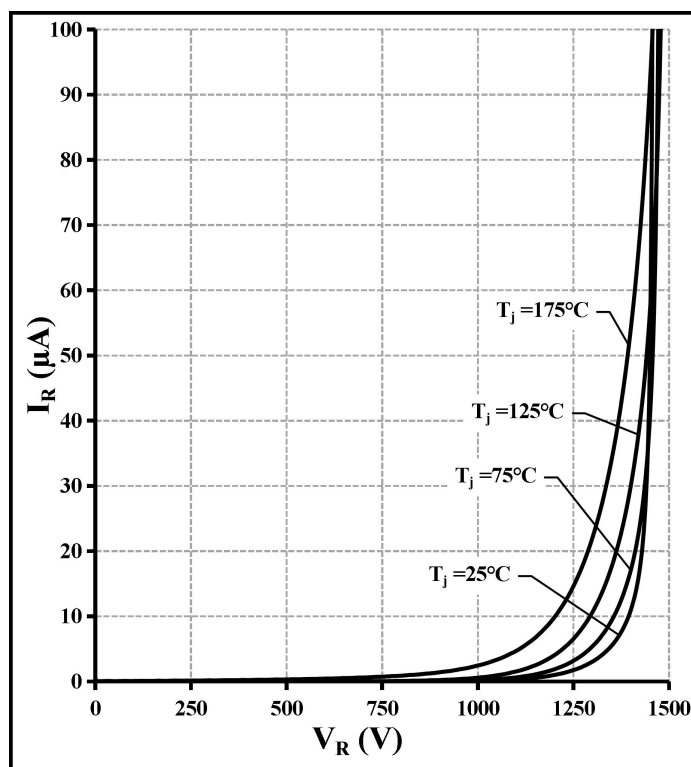


Figure 2: Reverse Characteristics

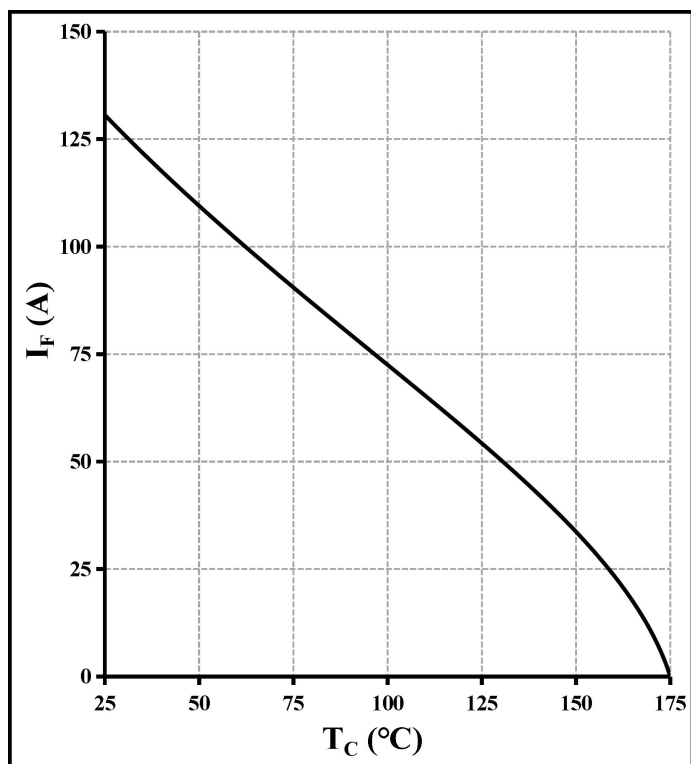


Figure 3: Current Derating

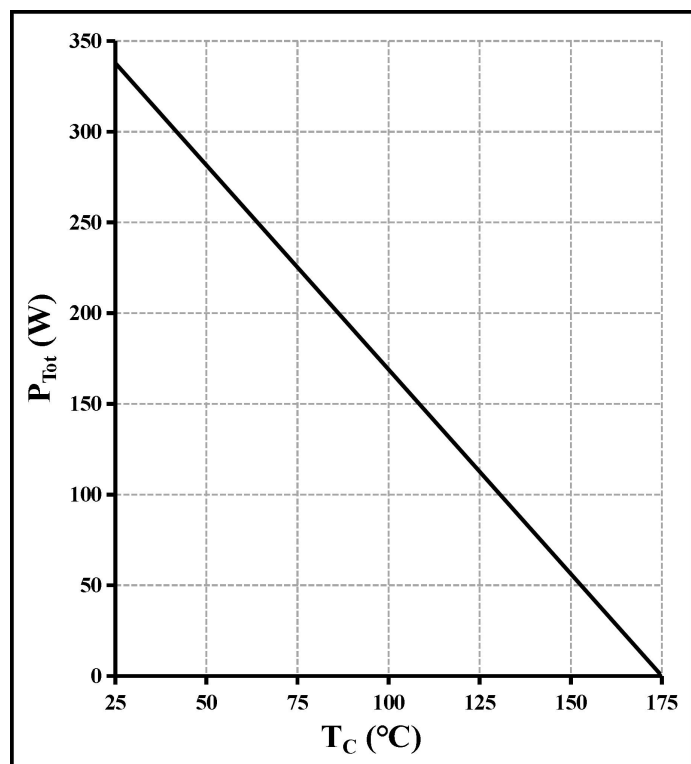


Figure 4: Power Derating

Typical Performance

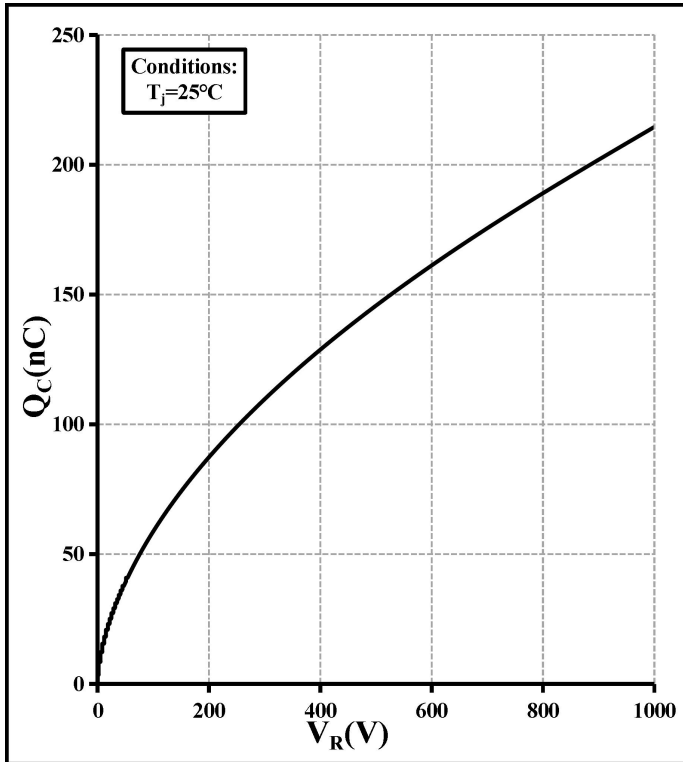


Figure 5: Total Capacitive Charge vs Reverse Voltage

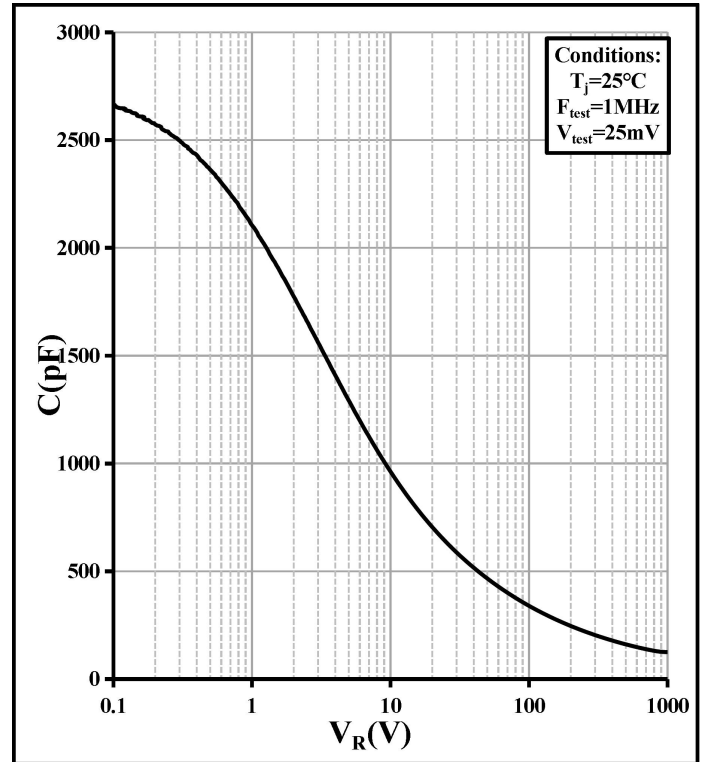


Figure 6: Total Capacitance vs Reverse Voltage

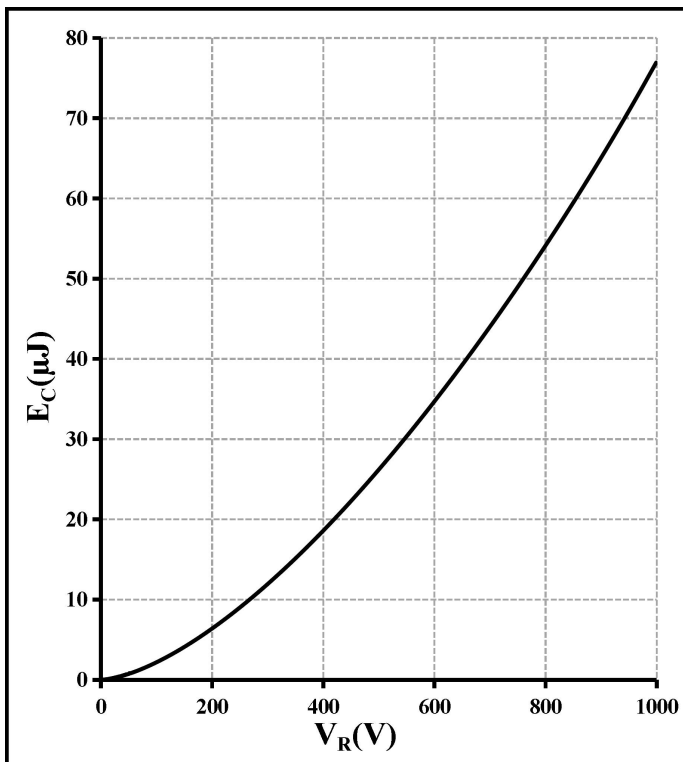


Figure 7: Typical Capacitance Stored Energy

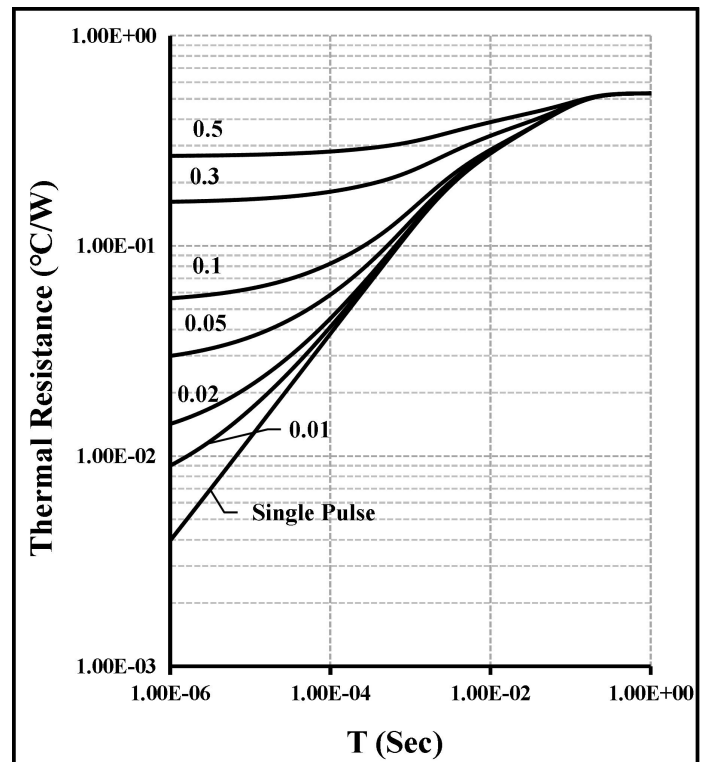


Figure 8: Transient Thermal Impedance

